

Teron™ SL670e XP

high performance reticle quality control system supports chip manufacturing by finding defects on EUV reticles that affect the yield of semiconductor chips

BENEFITS:

Operating at industry-leading production throughput, the Teron SL670e XP provides high sensitivity detection of reticle defects that can affect chip yield, reliability and performance. The Teron SL670e XP helps chipmakers:

- Perform incoming quality control (IQC) of reticles shipped from mask manufacturers by validating that the reticles are free of particle and other potentially printable defects before they enter the chip manufacturing production stream
- Requalify reticles after multiple cycles of production use by providing actionable data on contamination or progressive defects so that reticles can be accurately dispositioned for cleaning or for continued production use

TECHNOLOGIES:

- Defect sensitivity to support 5nm/3nm logic and advanced DRAM production
- Industry-best scan time
- Stringent EUV cleanliness requirements and advanced particle control
- EUVGold™ and EUVMultiDie algorithms
- Enhanced thermal stability
- Advanced focus tracking and expanded imaging flexibility

APPLICATIONS:

- Incoming reticle quality check
- Reticle requalification after production use or cleaning



MARKETS:

Chip manufacturing

EUV lithography applications including production of 5nm/3nm design node logic and advanced DRAM devices

PLATFORM:

- Customizable configurations
- Extendible
- Field upgrade from Teron SL670e

RETICLES:

- EUV reticles
- Option for advanced optical reticles